

*C*  
*B*  
an electrically conductive filler,

whereby the adhesive has anisotropic electrical conductivity.

*B*  
*C*  
4. (Twice Amended) The adhesive for semiconductor parts according to Claim 1, wherein the cyclic structure-containing thermoplastic polymer is at least one thermoplastic norbornene resin selected from the group consisting of (1) an addition (co)polymer of an alicyclic monomer having a norbornene ring, (2) an addition copolymer of an alicyclic monomer having a norbornene ring and a vinyl compound, (3) a ring-opening (co)polymer of an alicyclic monomer having a norbornene ring, and (4) a hydrogenated product of the ring-opening (co)polymer of the alicyclic monomer having a norbornene ring.

*B*  
5. (Twice Amended) The adhesive for semiconductor parts according to Claim 1, wherein the cyclic structure-containing thermoplastic polymer is at least one selected from the group consisting of an addition polymer of a cyclic conjugated diene monomer and a hydrogenated product of the addition polymer.

6. (Twice Amended) The adhesive for semiconductor parts according to Claim 1, wherein the cyclic structure-containing thermoplastic polymer is poly(phenylene ether).

8. (Third Amendment) The adhesive for semiconductor parts according to Claim 1, wherein the amount of the conductive filler is 1 to 100 parts by weight based on 100 parts by weight of the cyclic structure-containing thermoplastic polymer.

9. (Amended) The adhesive for semiconductor parts according to Claim 1, wherein the filler is a micro-capsulate conductive filler.

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10. (Third Amendment) The adhesive for semiconductor parts according to Claim 1, further comprising a low-molecular weight resin in a proportion of 1 to 50 parts by weight per 100 parts by weight of the cyclic structure-containing thermoplastic polymer.

*b3*  
12. (Amended) The adhesive for semiconductor parts according to Claim 2, wherein the cyclic structure-containing thermoplastic polymer is a modified polymer obtained by graft-modifying, with a functional group-containing unsaturated compound, a hydrogenated product of a ring-opening copolymer of tetracyclododecene or a derivative thereof,

an addition copolymer of tetracyclododecene or a derivative thereof and a vinyl compound, or

a hydrogenated product of an addition polymer of 1,3-cyclohexadiene.

*b4*  
15. (Third Amendment) The adhesive for semiconductor parts according to Claim 10, wherein the amount of the conductive filler is 1 to 100 parts by weight based on 100 parts by weight of the cyclic structure-containing thermoplastic polymer.

Please add the following claims 20-29:

--20. (NEW) A process for producing a semiconductor part package, which comprises laminating the adhesive film according to Claim 16 on the surface of a substrate having an electrode (A) thereon,  
*b5*  
placing a semiconductor part on the adhesive film,  
bonding the semiconductor part having an electrode (B) to the substrate to electrically connect the electrode (A) with the electrode (B), by heating and pressurizing the adhesive

film at a temperature not lower than the glass transition temperature of the cyclic structure-containing thermoplastic polymer, and then

cooling the adhesive film.--

--21. (NEW) A process for producing a semiconductor part package, which comprises

applying a solution of the adhesive according to Claim 1 on the surface of a substrate having an electrode (A) thereon,

drying a solvent from the solution to form an adhesive layer,

placing a semiconductor part on the adhesive layer,

bonding the semiconductor part having an electrode (B) to the substrate to electrically connect the electrode (A) with the electrode (B), by heating and pressurizing the adhesive layer at a temperature not lower than the glass transition temperature of the cyclic structure-containing thermoplastic polymer, and then

cooling the adhesive layer.--

*B5*  
--22. (NEW) The adhesive for semiconductor parts according Claim 1, wherein the filler has an average particle diameter of  $(\text{length} + \text{breadth})/2$  in the range of 0.1 to 30 $\mu\text{m}$ .--

--23. (NEW) The adhesive for semiconductor parts according Claim 1, wherein the filler has an average particle diameter of  $(\text{length} + \text{breadth})/2$  in the range of 1 to 20 $\mu\text{m}$ .--

--24. (NEW) The adhesive for semiconductor parts according Claim 1, wherein the filler has an average particle diameter of  $(\text{length} + \text{breadth})/2$  in the range of 5 to 15 $\mu\text{m}$ .--

--25. (NEW) The adhesive for semiconductor parts according Claim 1, wherein the cyclic structure-containing thermoplastic polymer has a number average molecular weight of 3,000 to 300,000.--

--26. (NEW) The adhesive for semiconductor parts according Claim 1, wherein the cyclic structure-containing thermoplastic polymer has a number average molecular weight of 5,000 to 250,000.--

--27. (NEW) The adhesive for semiconductor parts according Claim 1, wherein the amount of the conductive filler is 2 to 70 parts by weight based on 100 parts by weight of the cyclic structure-containing thermoplastic polymer.--

*BS*  
--28. (NEW) The adhesive for semiconductor parts according Claim 1, wherein the amount of the conductive filler is 3 to 50 parts by weight based on 100 parts by weight of the cyclic structure-containing thermoplastic polymer.--

--29. (NEW) The adhesive film according to Claim 16, which has a thickness of about 1 $\mu$ m to 1 mm.--